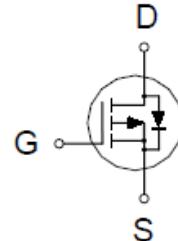
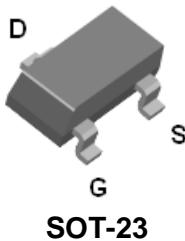


# PA406EM

## P-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
-60V	140mΩ @ $V_{GS} = -10V$	-2A



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current $T_A = 25^\circ C$	$I_D$	-2	A
		-1.5	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	-7	
Power Dissipation $T_A = 25^\circ C$	$P_D$	0.8	W
		0.5	
Operating Junction & Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient <sup>2</sup>	$R_{0JA}$		150	°C / W

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>The value of  $R_{0JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz Copper,in a still air environment with  $T_A=25^\circ C$ .The value in any given application depends on the user's specific board design.

# PA406EM

## P-Channel Enhancement Mode MOSFET

### ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-60			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1	-1.8	-3	
Gate-Body Leakage	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = -48\text{V}, V_{\text{GS}} = 0\text{V}$			-1	$\mu\text{A}$
		$V_{\text{DS}} = -40\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$			-10	
On-State Drain Current <sup>1</sup>	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = -5\text{V}, V_{\text{GS}} = -10\text{V}$	-7			A
Drain-Source On-State Resistance <sup>1</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = -10\text{V}, I_D = -1.5\text{A}$		93	140	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -1.5\text{A}$		118	210	
Forward Transconductance <sup>1</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = -5\text{V}, I_D = -1.5\text{A}$		7		S
<b>DYNAMIC</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -25\text{V}, f = 1\text{MHz}$		682		pF
Output Capacitance	$C_{\text{oss}}$			54		
Reverse Transfer Capacitance	$C_{\text{rss}}$			47		
Total Gate Charge <sup>2</sup>	$Q_g$	$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = -10\text{V}, I_D = -1.5\text{A}$		16		nC
Gate-Source Charge <sup>2</sup>	$Q_{\text{gs}}$			2.2		
Gate-Drain Charge <sup>2</sup>	$Q_{\text{gd}}$			4.6		
Turn-On Delay Time <sup>2</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = -30\text{V}$ $I_D \approx -1.5\text{A}, V_{\text{GS}} = -10\text{V}, R_{\text{GS}} = 6\Omega$		17		nS
Rise Time <sup>2</sup>	$t_r$			18		
Turn-Off Delay Time <sup>2</sup>	$t_{\text{d}(\text{off})}$			52		
Fall Time <sup>2</sup>	$t_f$			19		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ( <math>T_A = 25^\circ\text{C}</math> )</b>						
Continuous Current	$I_S$				-2	A
Forward Voltage <sup>1</sup>	$V_{\text{SD}}$	$I_F = -1.5\text{A}, V_{\text{GS}} = 0\text{V}$			-1	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F = -1.5\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		21		nS
Reverse Recovery Charge	$Q_{\text{rr}}$			18		nC

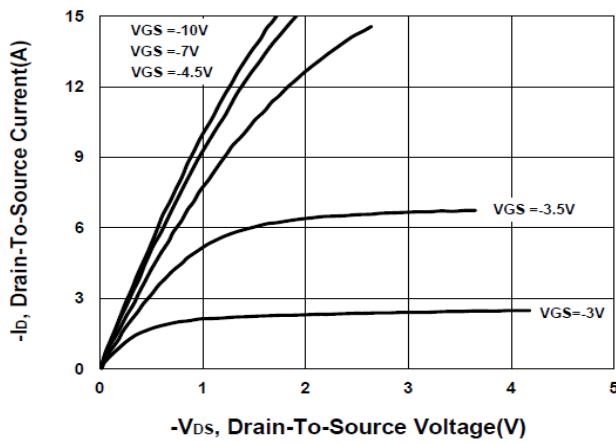
<sup>1</sup>Pulse test : Pulse Width  $\leq 300\text{ }\mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

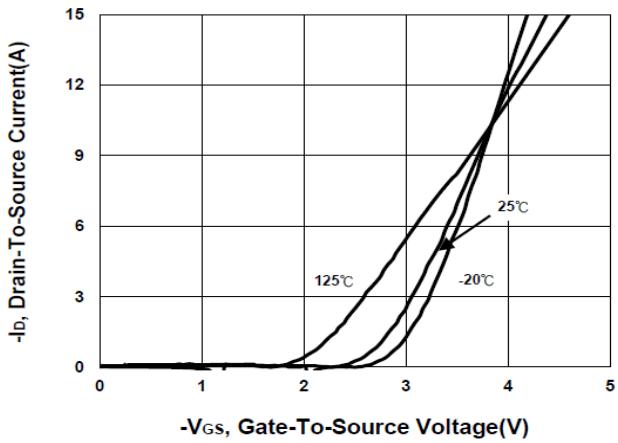
## PA406EM

### P-Channel Enhancement Mode MOSFET

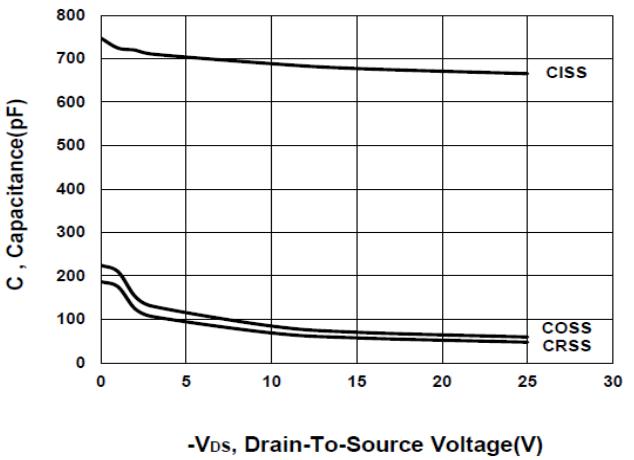
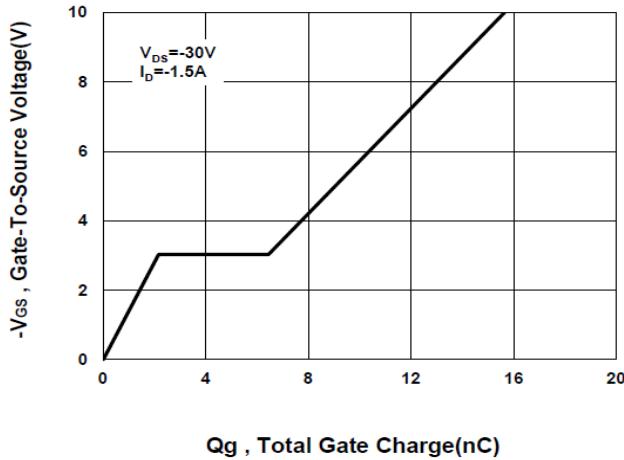
**Output Characteristics**



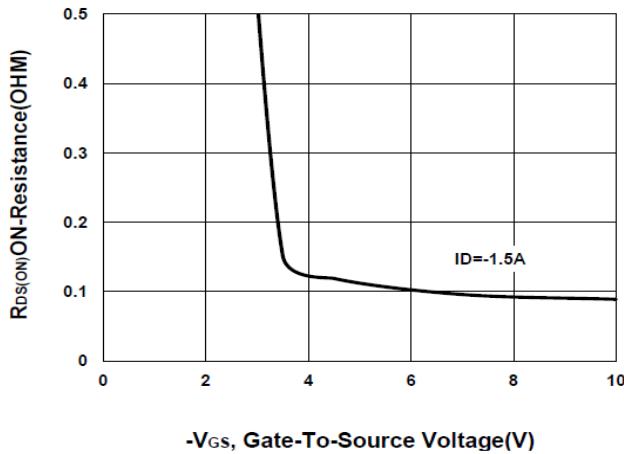
**Transfer Characteristics**



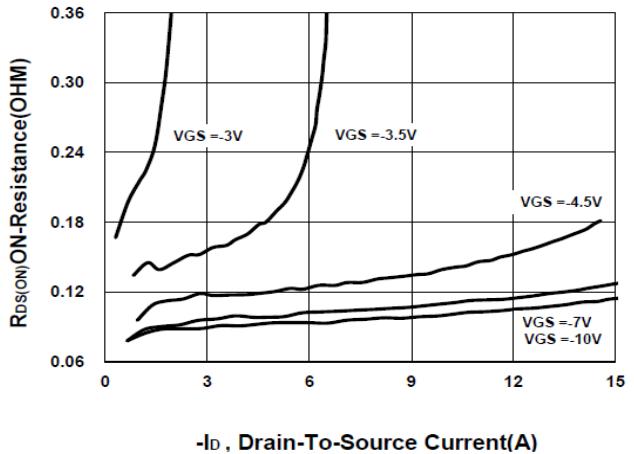
**Gate charge Characteristics**



**On-Resistance VS Gate-To-Source**

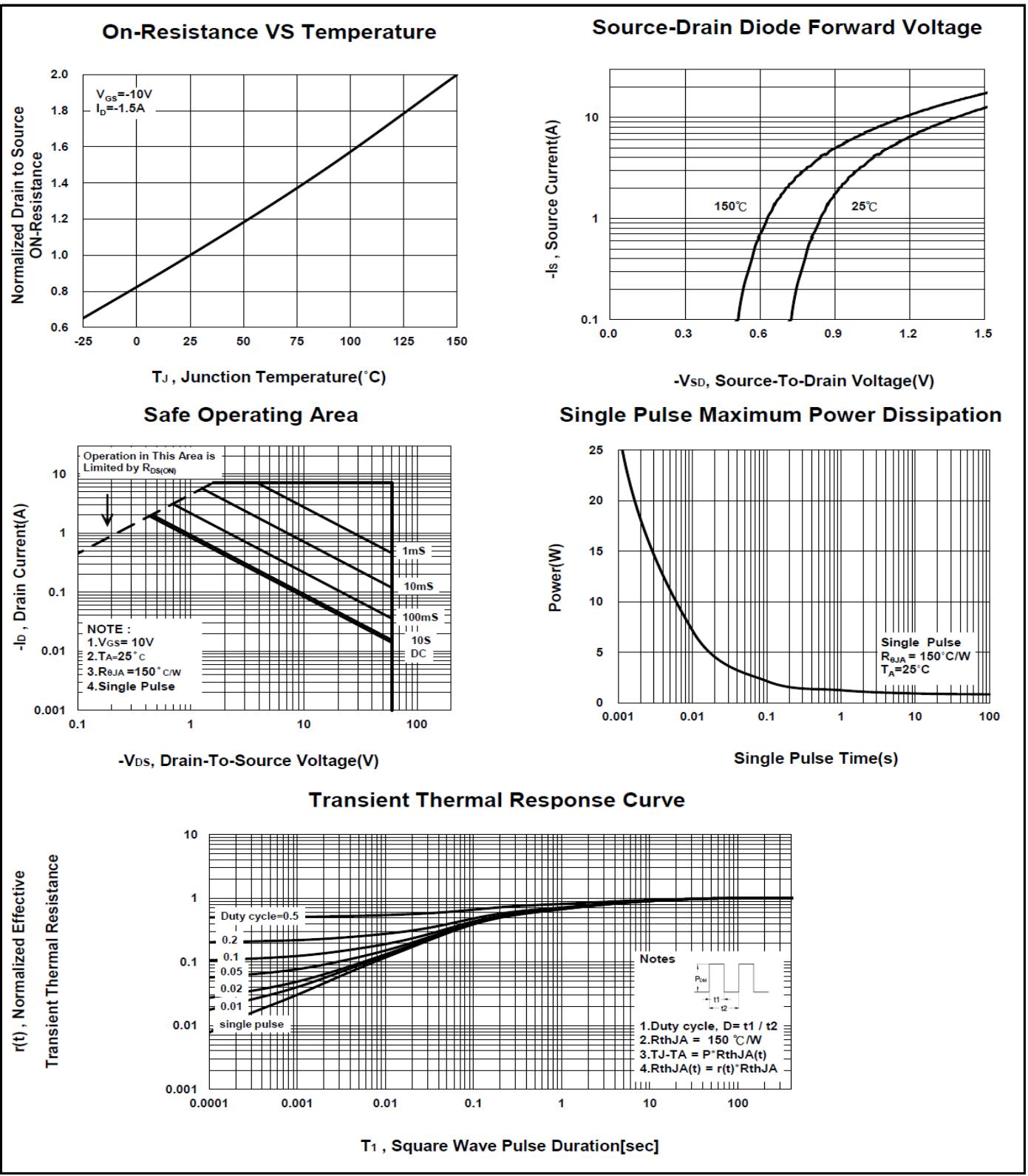


**On-Resistance VS Drain Current**



## PA406EM

### P-Channel Enhancement Mode MOSFET



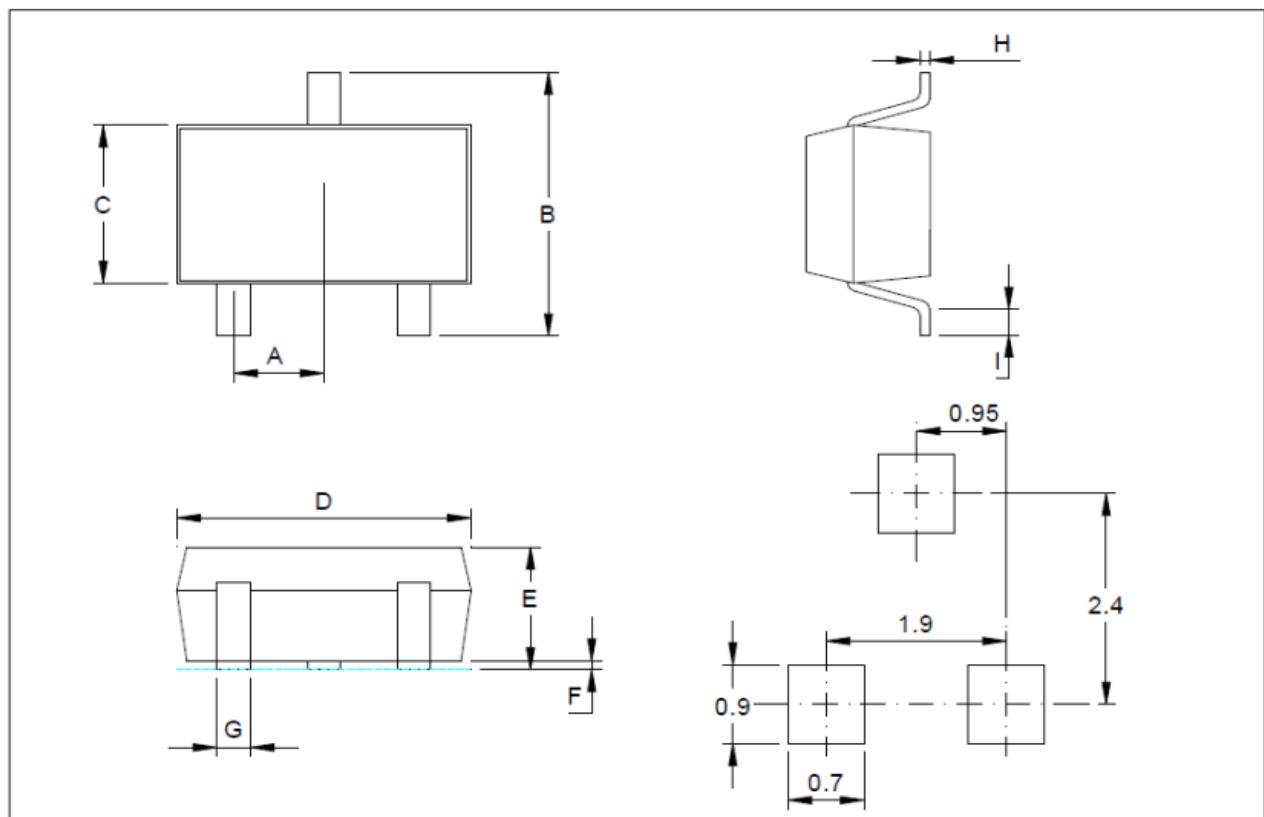
# PA406EM

## P-Channel Enhancement Mode MOSFET

### Package Dimension

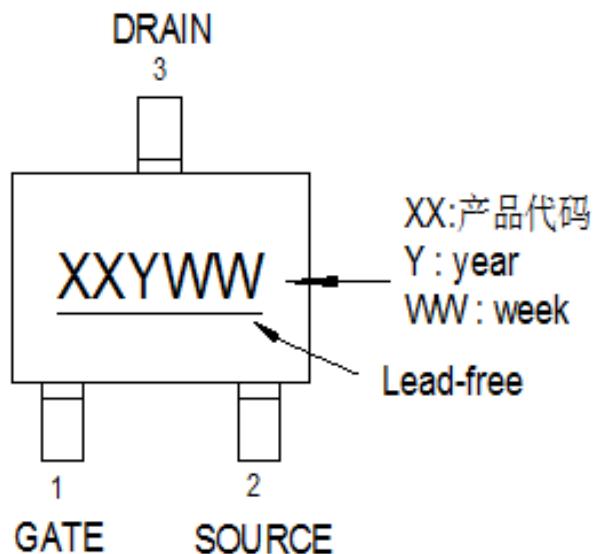
#### SOT-23 MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A		1.05		H	0.1		0.2
B	2.4		3	I	0.3		0.6
C	1.4		1.73				
D	2.7		3.1				
E	1		1.31				
F	0		0.15				
G	0.3		0.5				

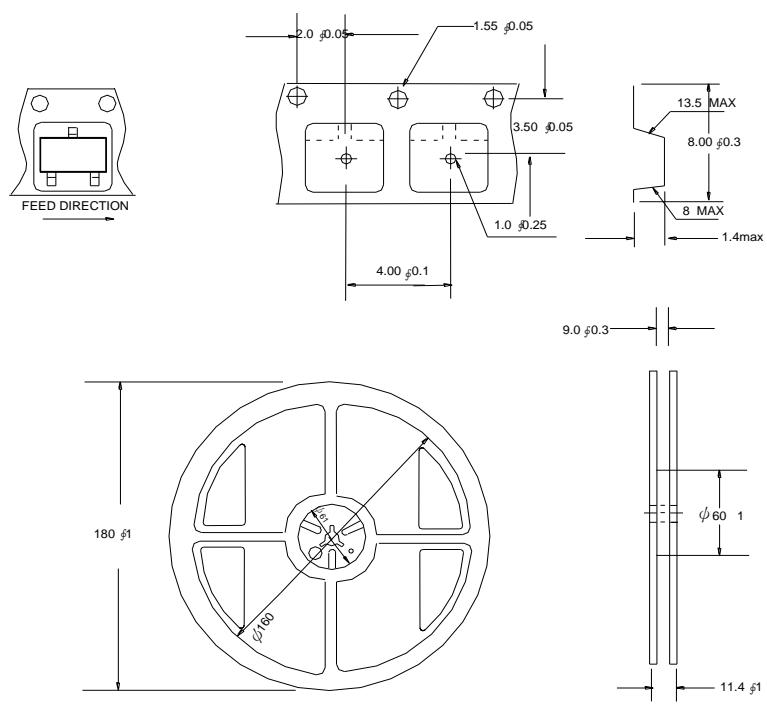


## PA406EM P-Channel Enhancement Mode MOSFET

### A. Marking Information (此产品代码为：2S)



### B. Tape&Reel Information: 3000pcs/Reel

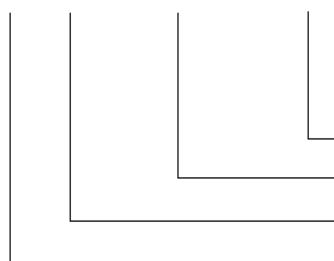


## **PA406EM** **P-Channel Enhancement Mode MOSFET**

### C. Lot.No. & Date Code rule

#### 1.LOT.NO.

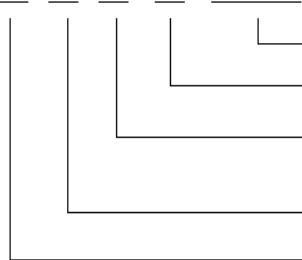
M N 15M21 03



- #8~9 Sub-lot No
- Order series no.
- Foundry site
- Assembly site

#### 2.Date Code

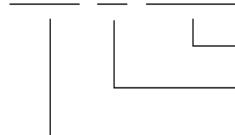
D Y M X XXX



- Order series no. & Sub-lot No
- Week
- M : Month (A:Jan , B:Feb , C:Mar ,D :Apr ,E:May ,F:Jun,G:Jul,H:Aug,I:Sep,J:Oct,K:Nov,L:Dec.)
- Y : Year (N : 2011, O : 2012 ...)
- Assembly site

#### 3.Date Code (for Small package)

XX Y WW



- Week
- Y : Year (9: 2009,A : 2010, B : 2011 ...)
- Device Name

## PA406EM P-Channel Enhancement Mode MOSFET

### D.Label rule

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文“0”和数字“0”，“G”和“Q”的字型即可)
3	Great Power	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	Pb Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 1 cm bottom color: Green Font color: Black Font style: Arial
12	Scan info	Device / Lot / D/C / QTY , Insert “ / ” between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least